



Product End-of-Life Disassembly Instructions

Product Category: Workstations

Marketing Name / Model

[List multiple models if applicable.]

HP Z200 Workstation

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Three in the power supply, one graphics card, and one system board. (Additional cards may be present depending on the configuration.)	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	None
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	None
Cathode Ray Tubes (CRT)		None
Capacitors / condensers (Containing PCB/PCT)		None
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		1
Gas Discharge Lamps		None
Plastics containing Brominated Flame Retardants	Include the system board, system fan, cooler fan, PSU socket inlet, PSU fan, and PSU fan housing	6
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	None
Components and waste containing asbestos		None
Components, parts and materials containing refractory ceramic fibers		None
Components, parts and materials containing radioactive substances		None

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.


Tool Description	Tool Size (if applicable)
Assorted Torx drivers, screwdrivers and a diagonal cutter	

3.0 Product Disassembly Process

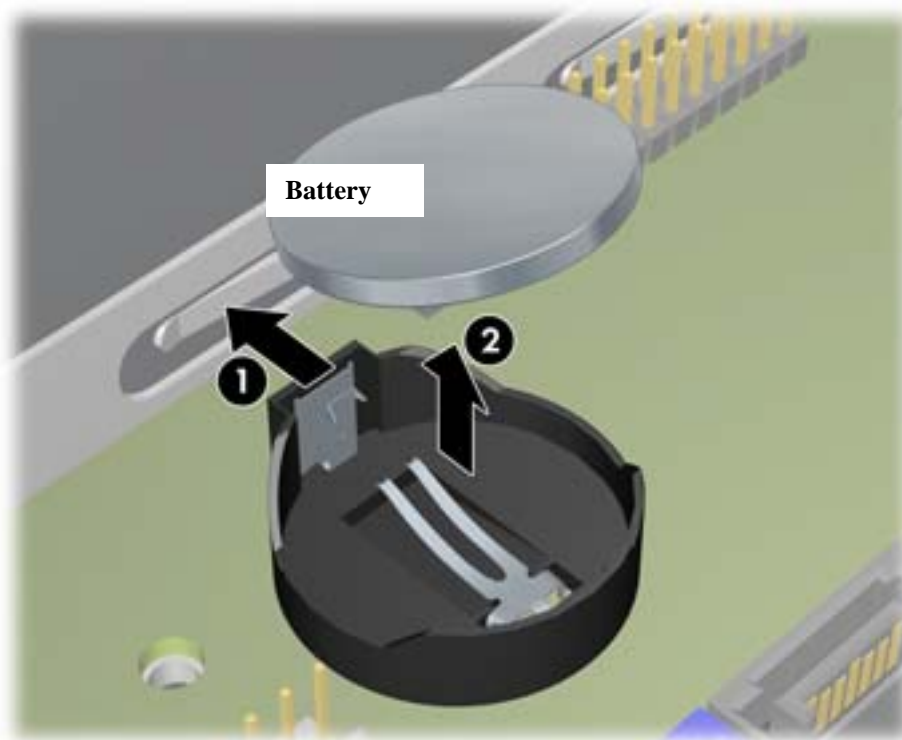
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

(See instructions below in sections 3.2 and 3.3.)

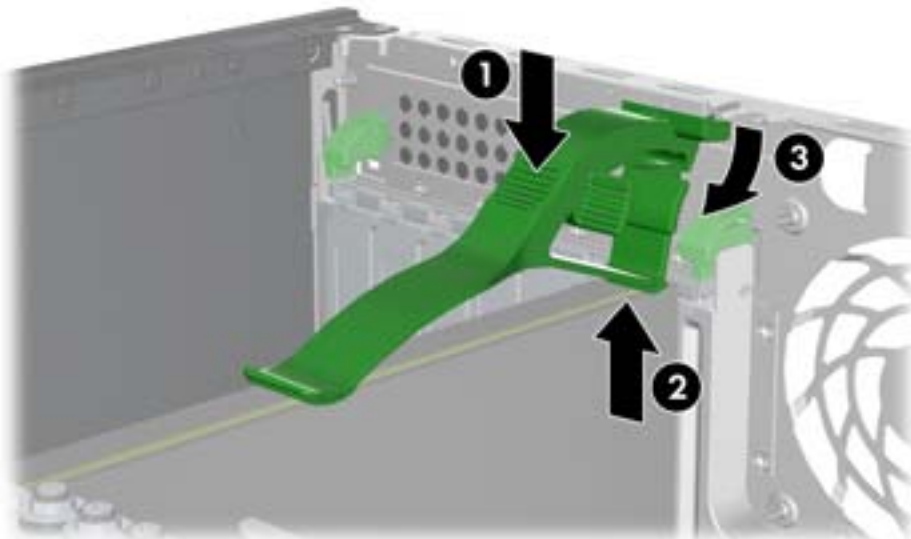
3.2 Workstation Disassembly Procedures

1.	Remove/disengage any security devices that prohibit opening the workstation.
2.	Disconnect the power cord from the electrical outlet and then from the workstation.
3.	Disconnect all peripheral device cables from the workstation.
4.	<p>Remove the access panel. Pull up on the handle (1), rotate the panel away from the chassis (2), then slide the front edge of the cover 1.3 CM (1/2 inch) toward the rear of the system to remove it (3) as shown in the following figure.</p>  <p>The diagram shows a workstation chassis with the top cover partially removed. Three numbered arrows indicate the disassembly steps: (1) an upward arrow pointing to a handle on the top cover; (2) a downward arrow pointing to the front edge of the cover; and (3) an upward arrow pointing to the front edge of the cover, indicating it is being slid towards the rear.</p>
5.	Disconnect all internal cables from system board, power supply, and other components.

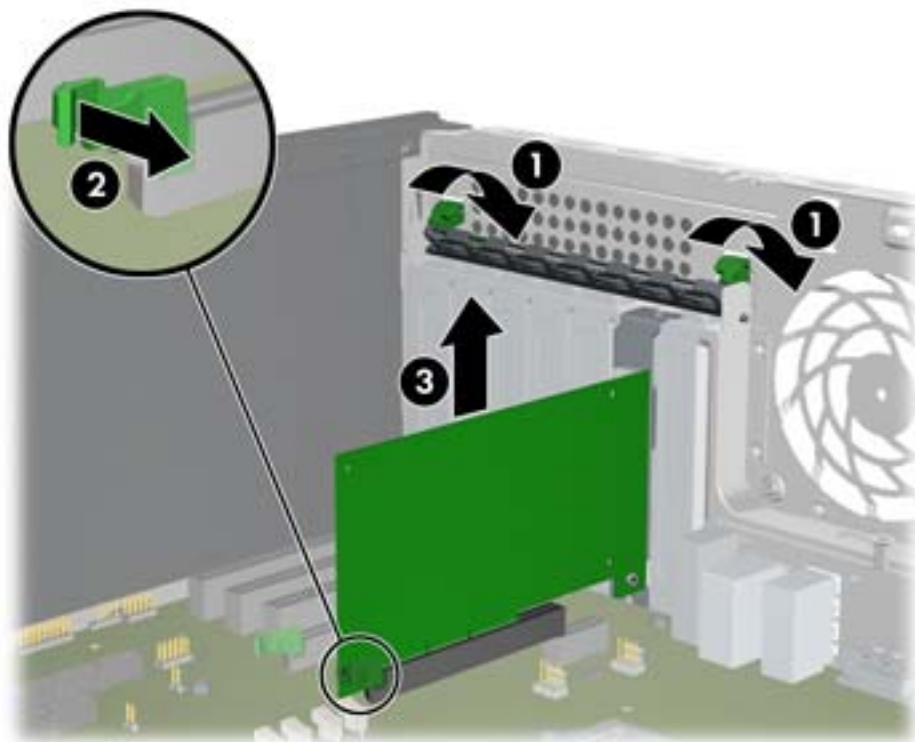
6. Remove the system battery. On the system board, press the release tab of the battery holder. Pull the tab (1) on the battery holder, and then lift it straight up (2) as shown in the following figure.



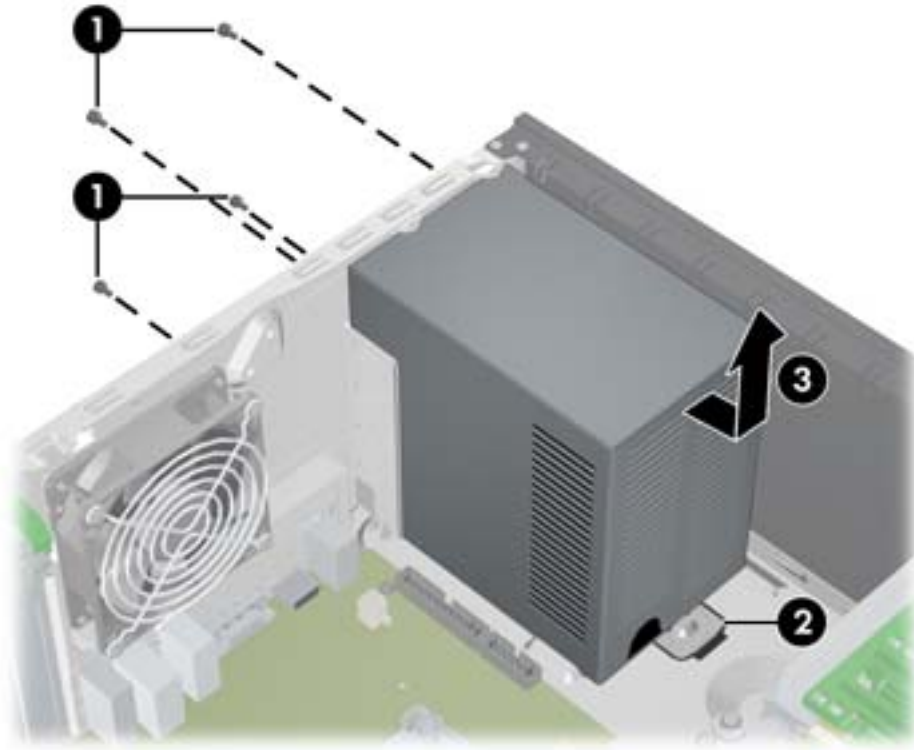
7. Remove the expansion card retainer (if installed): grasp the top of the clamp (1), squeeze the release handles until the bottom of the clamp releases from the clamp rail (2) (it should click when it releases), and swing the clamp out from the back panel (3).



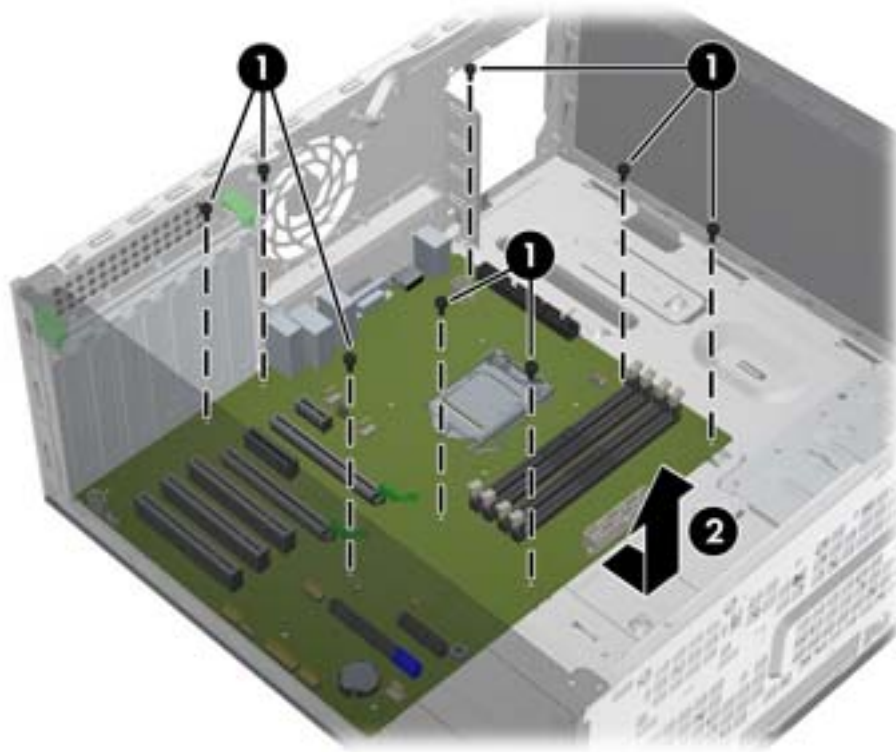
8. Remove all cables connected to the expansion card. Push down on the expansion card retention clamp levers on the inside of the chassis to open the retention clamp (1) as shown in the following figure. Release the expansion card slot latch (2), and then carefully lift the card from the chassis (3).



9. Remove the power supply from the chassis. Disconnect all of the power supply cables from the system board and all peripheral devices (hard drives, optical drives, and others as needed). Remove the four screws from the rear of the chassis (1) and then slide the power supply inward then up to remove it from the chassis (2).



10. Remove the system board. Remove the mounting screws (1) as shown in the following figure. Lift the system board slightly, and pull the board away from the rear of the chassis. Lift the system board upward out of the chassis (2).



11. Dispose of all removed components according to regulatory requirements.

3.3 Power Supply Disassembly Procedures

1. Refer to the Items Requiring Selective Treatment table to identify all components to be removed.

2. Cut the two cable ties at the rear of the unit. Cut the single cable tie at the side.



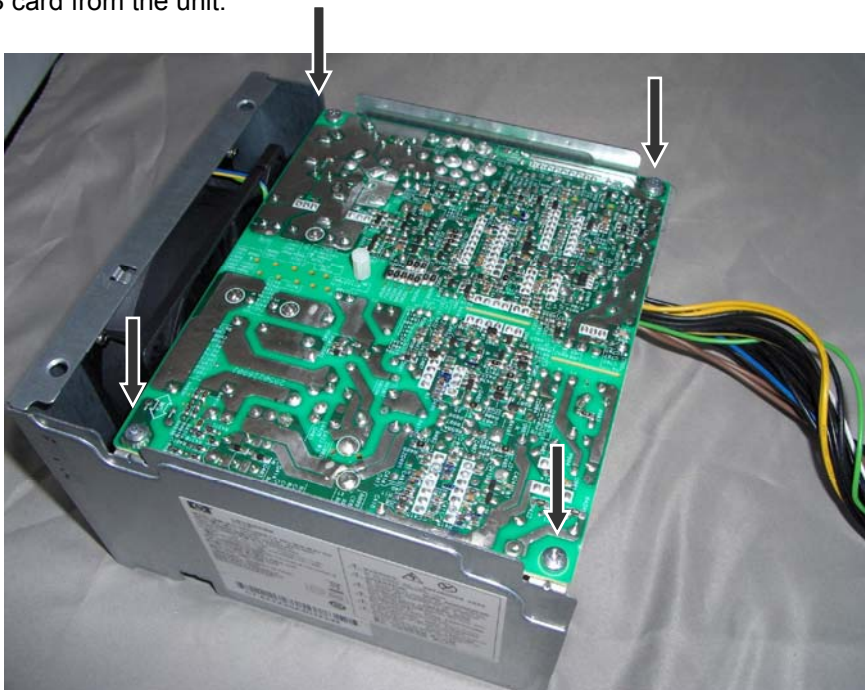
3. Remove the four power supply chassis screws—two from each side.



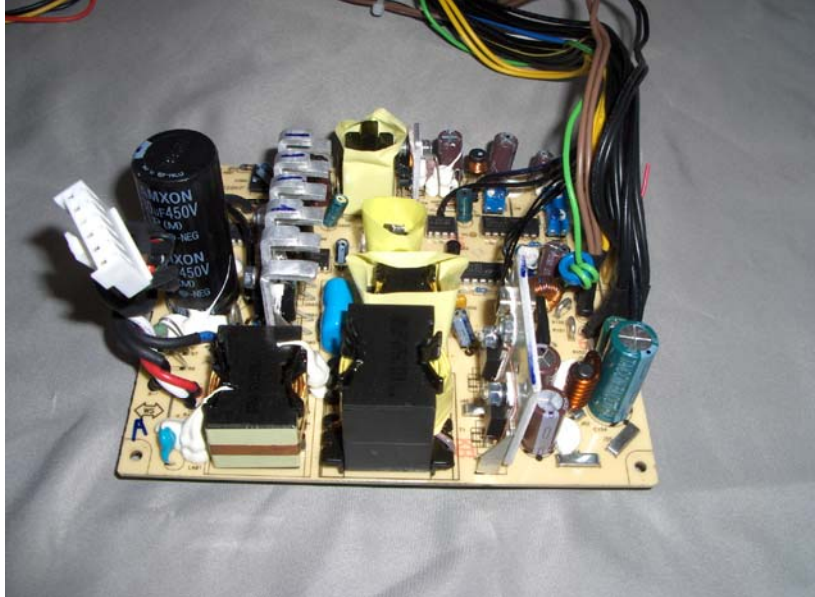
4. Slide the chassis housing from the power supply unit.



5. Remove the four screws from the corners of the large PCB card. Remove the large PCB card from the unit.



6. Use a diagonal cutter to remove the desired components from both PCB cards. (Note that some components may need to be unsoldered if a diagonal cutter does not fit between the component and the PCB card.)



7. Dispose of all removed components according to regulatory requirements.